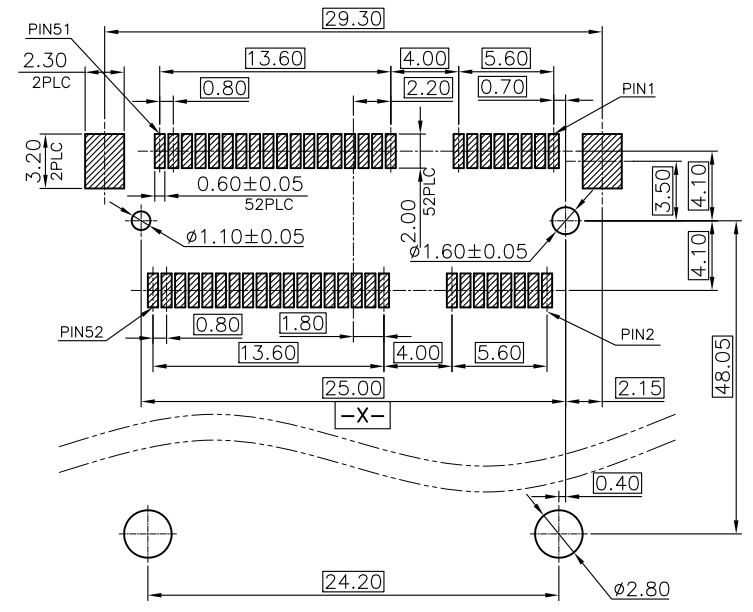
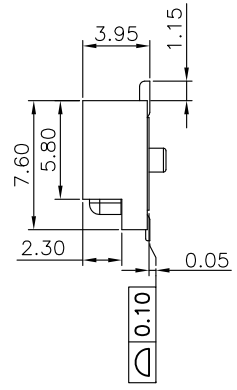
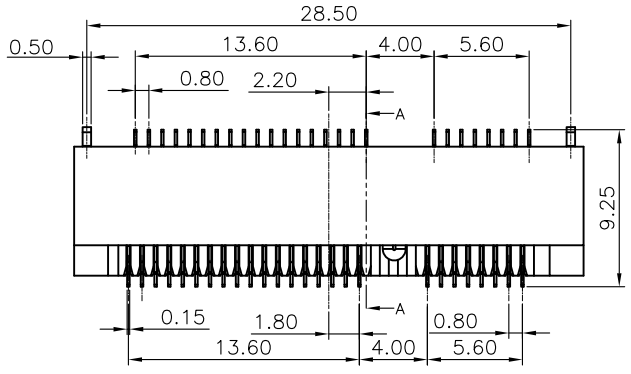
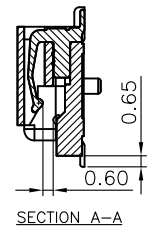
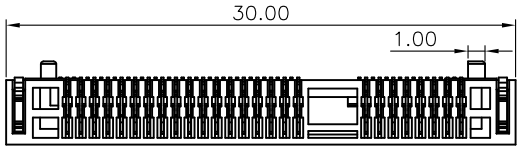
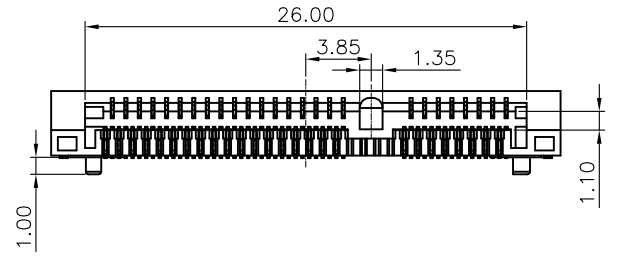


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2013/11/05	Jamie Zie
A1			Change coding principles	2013/11/13	Jamie Zie



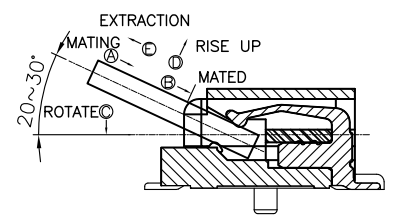
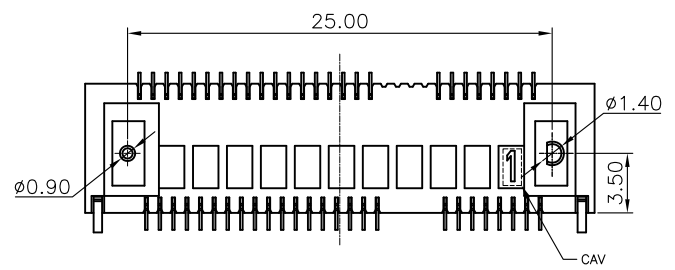
RECOMMEND PCB LAYOUT
TOLERANCES: ±0.05



NOTE:
1.MATERIAL:
HOUSING: HIGH TEMPARTURE THERMO PLASTIC UL
94V-0 Color:Black
CONTACT: COPPER ALLOY.
STATOR: COPPER ALLOY.
2.FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER AREA.
NICKEL UNPLATED OVER ALL.
STATOR: MATTER TIN PLATED ON NICKEL OVER ALL.

MATRIX PART NO:

MATRIX MINI PCI - MST 52 - 01 - 26
Pin Number - Series number
Planting
01:Gold Flash
15:15u"
30:30u"



HOW TO MATE AND UNMATE
SETP 1: MATE PROCESS A-B-C
SETP 2: UNMATE PROCESS D-E

NO	VARIETY	QTY	METERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°		DESIGN BY : Jamie Zie	DATE : 2013/11/13	PART NAME: MINI PCI (H=4.0mm)
APPROVED BY1: Richard Hsieh		DATE : 2013/11/13	PART NO.	MST52-01-26
APPROVED BY2: Richard Hsieh		DATE : 2013/11/13	MOLD NO.	NA
UNIT: mm [inch]		DATE :	DRAW NO.	
SCALE:1:1 SIZE:A4		DATE : 2013/11/13	SHEET NO.	1 OF 1